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(54) INTEGRATED FAN-OUT PACKAGE

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(57)ABSTRACT

An integrated fan-out (InFO) package includes a die, an encapsulant, and a horn antenna. The die has an active surface and a rear surface opposite to the active surface. The encapsulant laterally encapsulates the die. The horn antenna is electrically connected to the die. The horn antenna includes a top wall and a bottom wall respectively located on two opposite sides of the die and the encapsulant.

A portion of the top wall is located within a span of the active surface of the die. A portion of the bottom wall is located within a span of the rear surface of the die.

